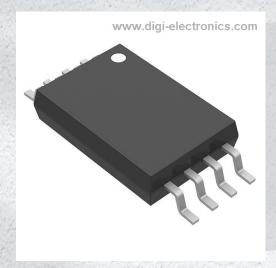


TL3016CPWR Datasheet



https://www.DiGi-Electronics.com

DiGi Electronics Part Number TL3016CPWR-DG

Manufacturer Texas Instruments

Manufacturer Product Number TL3016CPWR

Description IC COMPARATOR 1 W/LATCH 8TSSOP

Detailed Description Comparator with Latch Complementary, Push-Pull,

TTL 8-TSSOP



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.



Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
TL3016CPWR	Texas Instruments
Series:	Product Status:
	Active
Type:	Number of Elements:
with Latch	1
Output Type:	Voltage - Supply, Single/Dual (±):
Complementary, Push-Pull, TTL	5V ~ 10V, ±2.5V ~ 5V
Voltage - Input Offset (Max):	Current - Input Bias (Max):
3mV @ ±5V	10μA @ ±5V
Current - Output (Typ):	Current - Quiescent (Max):
20mA	12.5mA
CMRR, PSRR (Typ):	Propagation Delay (Max):
97dB CMRR	10ns
Hysteresis:	Operating Temperature:
	0°C ~ 70°C
Package / Case:	Mounting Type:
8-TSSOP (0.173", 4.40mm Width)	Surface Mount
Supplier Device Package:	Base Product Number:
8-TSSOP	TL3016

Environmental & Export classification

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	

8542.39.0001

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- **Ultrafast Operation . . . 7.6 ns (Typ)**
- **Low Positive Supply Current** 10.6 mA (Typ)
- Operates From a Single 5-V Supply or From a Split ±5-V Supply
- **Complementary Outputs**
- **Low Offset Voltage**
- No Minimum Slew Rate Requirement
- **Output Latch Capability**
- **Functional Replacement to the LT1016**

description

The TL3016 is an ultrafast comparator designed to interface directly to TTL logic while operating from either a single 5-V power supply or dual ±5-V supplies. It features extremely tight offset voltage and high gain for precision applications. It has complementary outputs that can be latched using the LATCH ENABLE terminal. Figure 1 shows the positive supply current of this comparator. The TL3016 only requires 10.6 mA (typical) to achieve a propagation delay of 7.6 ns.

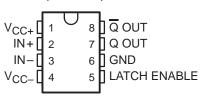
The TL3016 is a pin-for-pin functional replacement for the LT1016 comparator, offering higher speed operation but consuming half the power.

AVAILABLE OPTIONS

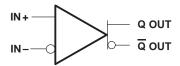
	PACKAG	CUID	
TA	SMALL OUTLINE† (D)	TSSOP (PW)	CHIP FORM [‡] (Y)
0°C to 70°C	TL3016CD	TL3016CPWLE	TL3016Y
-40°C to 85°C	TL3016ID	TL3016IPWLE	_

[†]The PW packages are available left-ended taped and reeled only. ‡ Chip forms are tested at $T_A = 25^{\circ}$ C only.

D AND PW PACKAGE (TOP VIEW)



symbol (each comparator)



POSITIVE SUPPLY CURRENT FREE-AIR TEMPERATURE

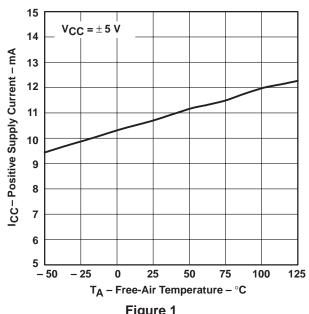


Figure 1



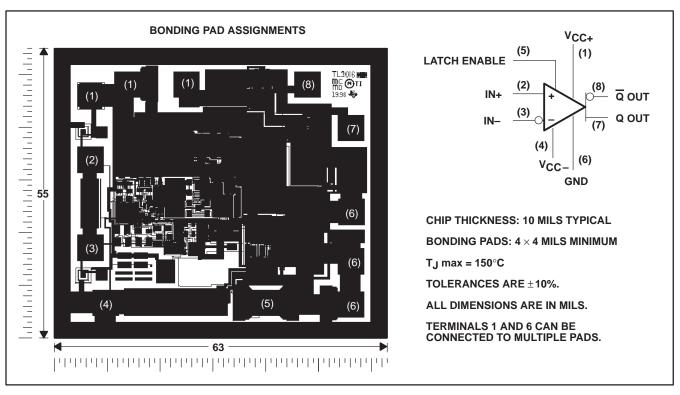
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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TL3016Y chip information

This chip displays characteristics similar to the TL3016C. Thermal compression or ultrasonic bonding may be used on the doped-aluminum bonding pads. Chips may be mounted with conductive epoxy or a gold-silicon preform.



COMPONENT C	OUNT
Bipolars	53
MOSFETs	49
Resistors	46
Capacitors	14



TL3016, TL3016Y ULTRA-FAST LOW-POWER PRECISION COMPARATORS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{DD} (see Note 1)	
Differential input voltage, V _{ID} (see Note 2)	
Input voltage range, V ₁	
Input voltage, V _I (LATCH ENABLE)	
Output current, I _O	± 20 m/
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	–40°C to 85°C
Storage temperature range, T _{stq}	– 65°C to 150°C
Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds	

NOTES: 1. All voltage values, except differential voltages, are with respect to network ground.

2. Differential voltages are at IN+ with respect to IN-.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW
PW	525 mW	4.2 mW/°C	336 mW



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

TL3016, TL3016Y ULTRA-FAST LOW-POWER PRECISION COMPARATORS

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electrical characteristics at specified operating free-air temperature, V_{DD} = ± 5 V, V_{LE} = 0 (unless otherwise noted)

PARAMETER				TL3016C	;		UNIT			
	PARAMETER	TEST CONDI	TIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNII
V/10	Input offset voltage	T _A = 25°C			0.5	3		0.5	3	mV
VIO	input onset voitage	T _A = full range				3.5			3.5	IIIV
ανιο	Temperature coefficient of input offset voltage				-4.8			-4.5		μV/°C
1	logue effect current	T _A = 25°C			0.1	0.6		0.1	0.6	
lio	Input offset current	T _A = full range				0.9			1.3	μΑ
l.s	Input bias current	T _A = 25°C			6	10		6	10	
IB	input bias current	T _A = full range				10			10	μΑ
\/.op	Common-mode input	$V_{DD} = \pm 5 \text{ V}$		-3.75		3.5	-3.75		3.5	V
VICR	voltage range	V _{DD} = 5 V		1.25		3.5	1.25		3.5	v
CMRR	Common-mode rejection ratio	$-3.75 \le V_{IC} \le 3.5 V$,	T _A = 25°C	80	97		80	97		dB
, Supply-voltage rejection	Positive supply: 4.6 V ≤ T _A = 25°C	\leq +V _{DD} \leq 5.4 V,	60	72		60	72		dB	
ksvR ratio		Negative supply: -7 V	80	100		80	100		иь	
\/a:	Low-level output voltage	$I_{\text{(sink)}} = 4 \text{ mA},$ $T_{\text{A}} = 25^{\circ}\text{C}$	V+ ≤ 4.6 V,		500	600		500	600	mV
VOL	Low-level output voltage	$I_{(sink)} = 10 \text{ mA},$ $T_A = 25^{\circ}\text{C}$	V+ ≤ 4.6 V,		750			750		IIIV
Vон	High-level output voltage	V+ ≤ 4.6 V, T _A = 25°C	$I_O = 1 \text{ mA},$	3.6	3.9		3.6	3.9		V
VOH	riigii-ieveroutput voitage	V+ ≤ 4.6 V, T _A = 25°C	$I_{O} = 10 \text{ mA},$	3.4	3.7		3.4	3.7		v
la a	Positive supply current	T _A = full range			10.6	12.5		10.6	12.5	mA
IDD	Negative supply current	TA = Tull Tarige		-1.8	-1.3		-2.4	-1.3		IIIA
V _{IL}	Low-level input voltage (LATCH ENABLE)					0.8			0.8	V
VIH	High-level input voltage (LATCH ENABLE)			2			2			V
1	Low-level input current	V _{LE} = 0			0	1		0	1	
IIL	(LATCH ENABLE)	V _{LE} = 2 V			24	39		24	45	μΑ

[†] Full range for the TL3016C is $T_A = 0^{\circ}$ C to 70° C. Full range for the TL3016I is $T_A = -40^{\circ}$ C to 85° C. ‡ All typical values are measures with $T_A = 25^{\circ}$ C.



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switching characteristics, $V_{DD} = \pm 5 \text{ V}$, $V_{LE} = 0$ (unless otherwise noted)

DADAMETED			TEST CONDITIONS†			TL3016C			TL3016I		
	PARAMETER					MAX	MIN	TYP	MAX	UNIT	
^t pd1		$\Delta V_{I} = 100 \text{ mV},$	T _A = 25°C		7.8	10		7.8	10		
	Propagation delay time‡	$V_{OD} = 5 \text{ mV}$	T _A = full range		7.8	11.2		7.8	12.2	20	
		$\Delta V_I = 100 \text{ mV},$ $V_{OD} = 20 \text{ mV}$	T _A = 25°C		7.6	10		7.6	10	ns	
			T _A = full range		7.6	11.2		7.6	12.2		
t _{sk(p)}	Pulse skew (t _{pd+} - t _{pd} -)	$\Delta V_I = 100 \text{ mV},$ $T_A = 25^{\circ}\text{C}$	$V_{OD} = 5 \text{ mV},$		0.5			0.5		ns	
t _{su}	Setup time, LATCH ENABLE				2.5			2.5		ns	

TYPICAL CHARACTERISTICS

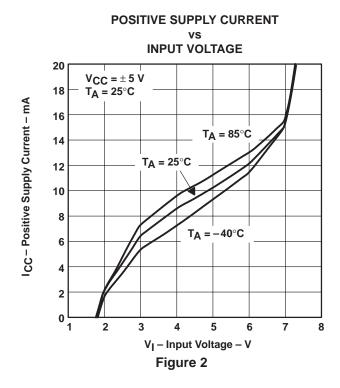
Table of Graphs

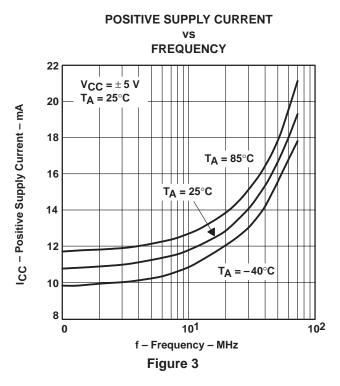
			FIGURE
		vs Input voltage	2
Icc	Positive supply current	vs Frequency	3
		vs Free-air temperature	4
ICC	Negative supply current	vs Free-air temperature	5
		vs Overdrive voltage	6
^t pd		vs Supply voltage	7
	Propagation delay time	vs Input impedance	8
		vs Load capacitance	9
		vs Free-air temperature	10
VIC	Common-mode input voltage	vs Free-air temperature	11
	Input threshold voltage (LATCH ENABLE)	vs Free-air temperature	12
\/-	Output valtage	vs Output source current	13
Vo	Output voltage	vs Output sink current	14
II	Input current (LATCH ENABLE)	vs Input voltage	15

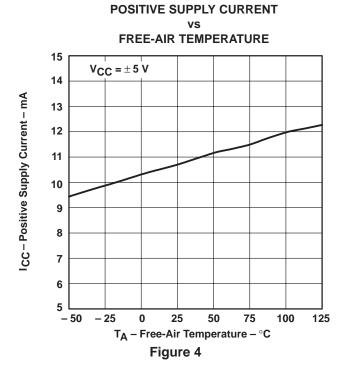
Full range for the TL3016C is 0°C to 70°C. Full range for the TL3016I is -40°C to 85°C.

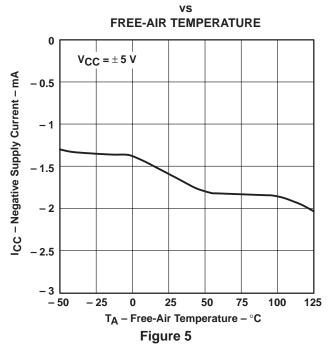
† tpd1 cannot be measured in automatic handling equipment with low values of overdrive. The TL3016 is 100% tested with a 1-V step and 500-mV overdrive at TA = 25°C only. Correlation tests have shown that tpd1 limits given can be ensured with this test, if additional dc tests are performed to ensure that all internal bias conditions are correct. For low overdrive conditions, Vos is added to the overdrive.

TYPICAL CHARACTERISTICS



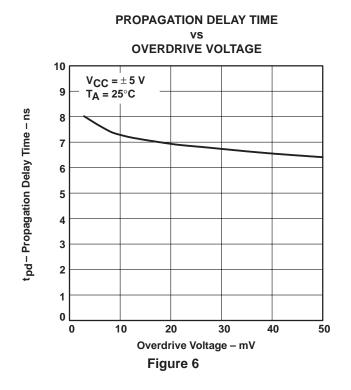


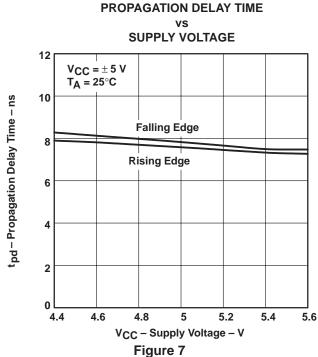


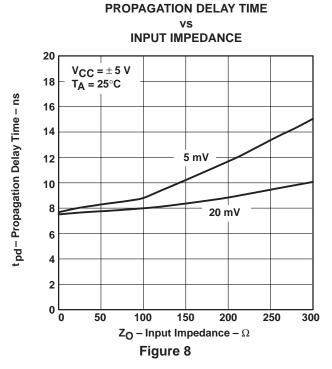


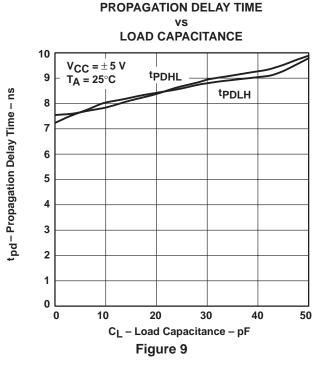
NEGATIVE SUPPLY CURRENT

TYPICAL CHARACTERISTICS

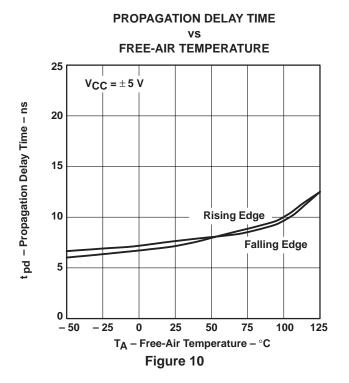


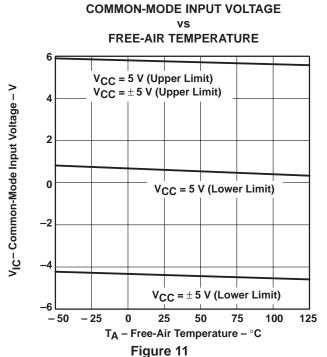




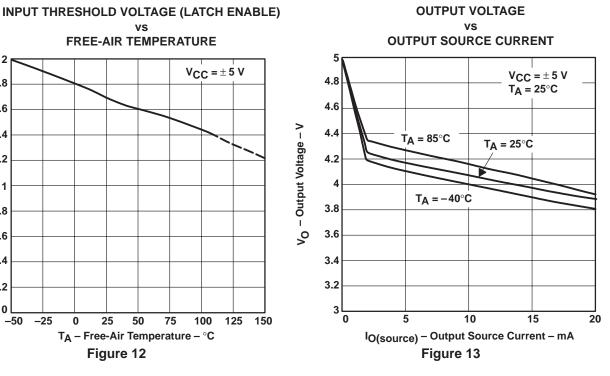


TYPICAL CHARACTERISTICS



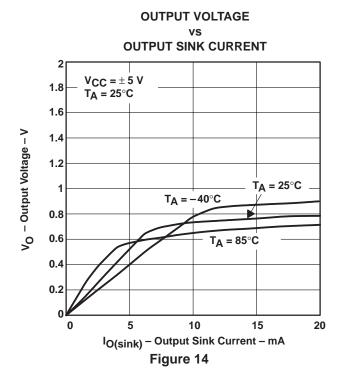


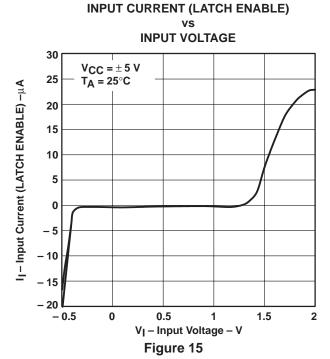
vs FREE-AIR TEMPERATURE V_{IT} – Input Threshold Voltage (LATCH ENABLE) – V $V_{CC} = \pm 5 V$ 1.8 1.6 1.4 1.2 1 0.8 0.6 0.4 0.2 50 -50 -25 25 75 100 125 TA - Free-Air Temperature - °C Figure 12



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TYPICAL CHARACTERISTICS







PACKAGE OPTION ADDENDUM

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PACKAGING INFORMATION

Orderable Device	Status	Package Typ	e Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL3016CD	ACTIVE	SOIC	D	8	75	RoHS & Green	(6) NIPDAU	Level-1-260C-UNLIM	0 to 70	3016C	_
11301000	ACTIVE	3010	U	0	75	Kons & Green	NIPDAU	Level-1-200C-UNLIM	0 10 70	30100	Samples
TL3016CDG4	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	3016C	Samples
TL3016CDR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	3016C	Samples
TL3016CPW	ACTIVE	TSSOP	PW	8	150	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	T3016	Samples
TL3016CPWR	ACTIVE	TSSOP	PW	8	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	T3016	Samples
TL3016ID	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	3016I	Samples
TL3016IDR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	3016I	Samples
TL3016IDRG4	ACTIVE	SOIC	D	8	2500	TBD	Call TI	Call TI	-40 to 85		Samples
TL3016IPW	ACTIVE	TSSOP	PW	8	150	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3016	Samples
TL3016IPWR	ACTIVE	TSSOP	PW	8	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3016	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

TL3016CPWR Texas Instruments IC COMPARATOR 1 W/LATCH 8TSSOP



PACKAGE OPTION ADDENDUM

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(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL3016CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3016CPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TL3016IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3016IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1



PACKAGE MATERIALS INFORMATION

www.ti.com 5-Dec-2023



*All dimensions are nominal

_	7 th difference are formula.										
	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)			
	TL3016CDR	SOIC	D	8	2500	350.0	350.0	43.0			
	TL3016CPWR	TSSOP	PW	8	2000	356.0	356.0	35.0			
	TL3016IDR	SOIC	D	8	2500	350.0	350.0	43.0			
	TL3016IPWR	TSSOP	PW	8	2000	367.0	367.0	35.0			



PACKAGE MATERIALS INFORMATION

www.ti.com 5-Dec-2023

TUBE



*All dimensions are nominal

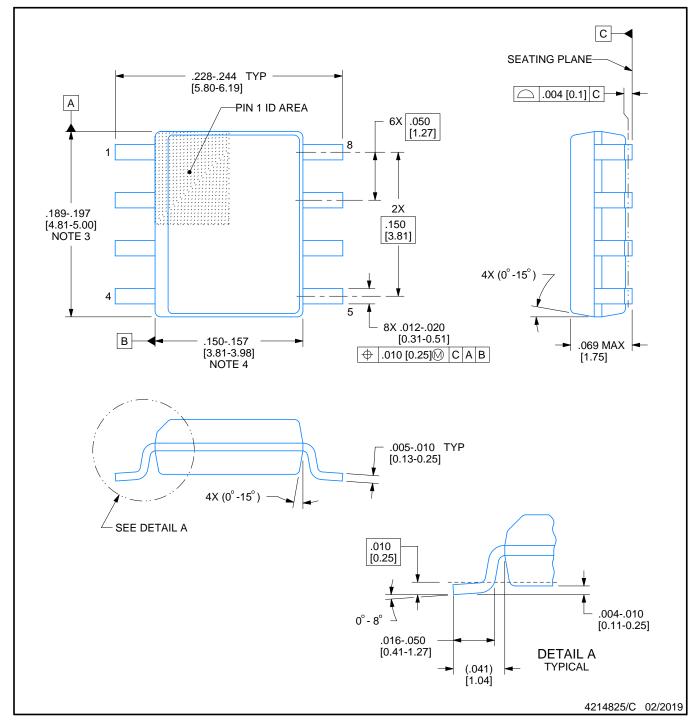
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
TL3016CD	D	SOIC	8	75	505.46	6.76	3810	4
TL3016CDG4	D	SOIC	8	75	505.46	6.76	3810	4
TL3016CPW	PW	TSSOP	8	150	530	10.2	3600	3.5
TL3016ID	D	SOIC	8	75	505.46	6.76	3810	4
TL3016IPW	PW	TSSOP	8	150	530	10.2	3600	3.5



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

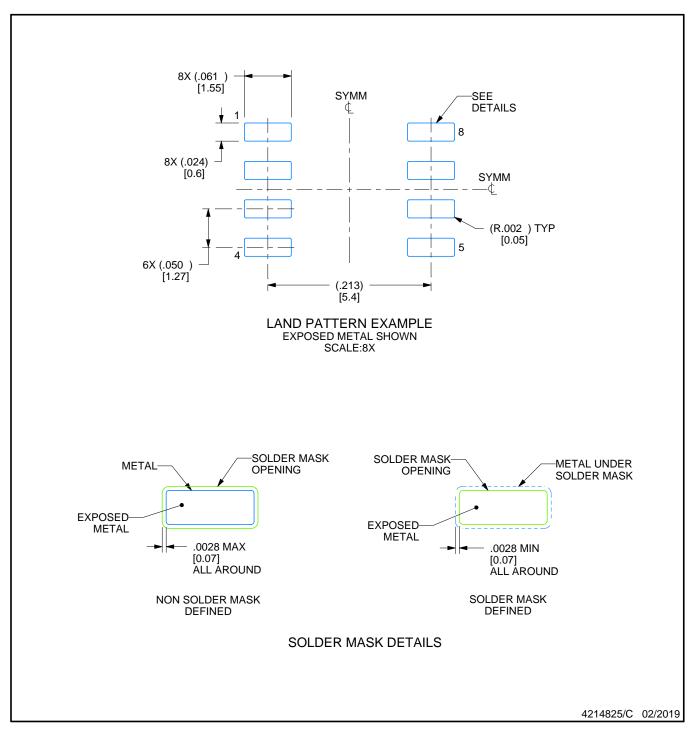
D0008A

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



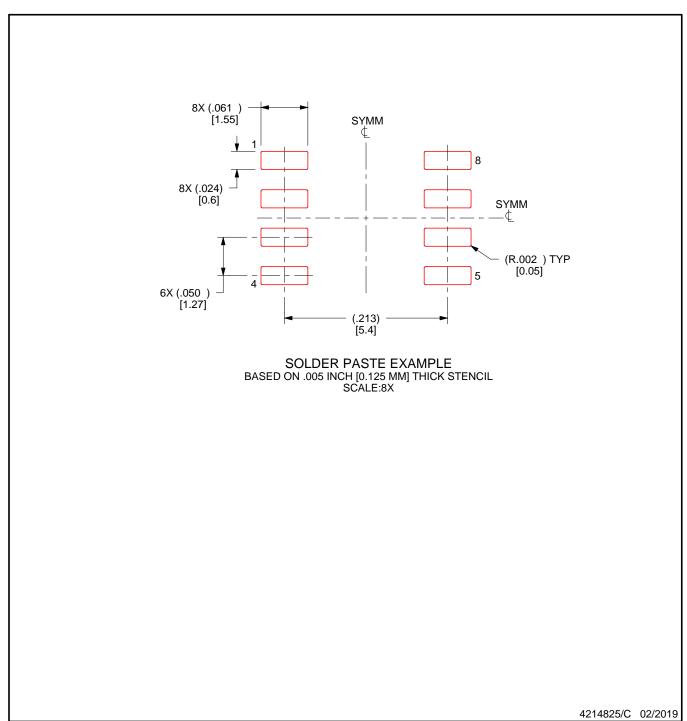
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



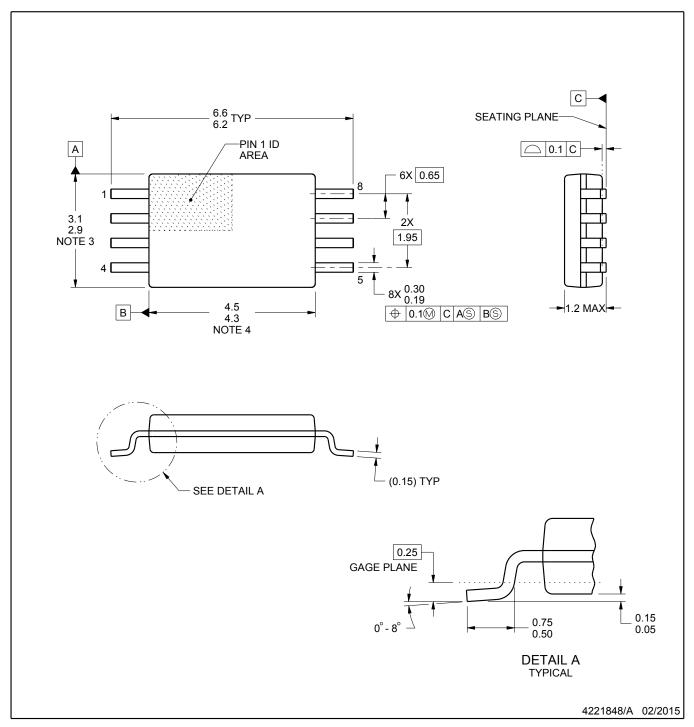
PW0008A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

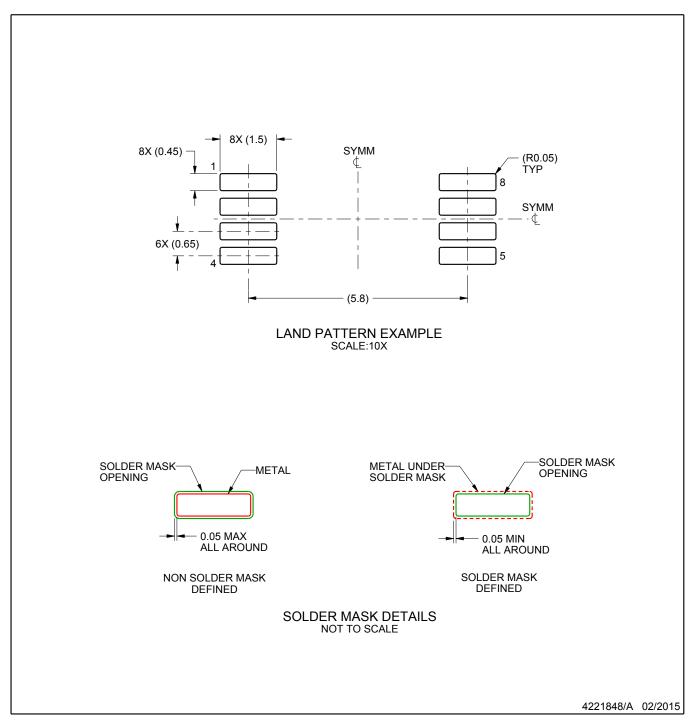
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153, variation AA.



SMALL OUTLINE PACKAGE



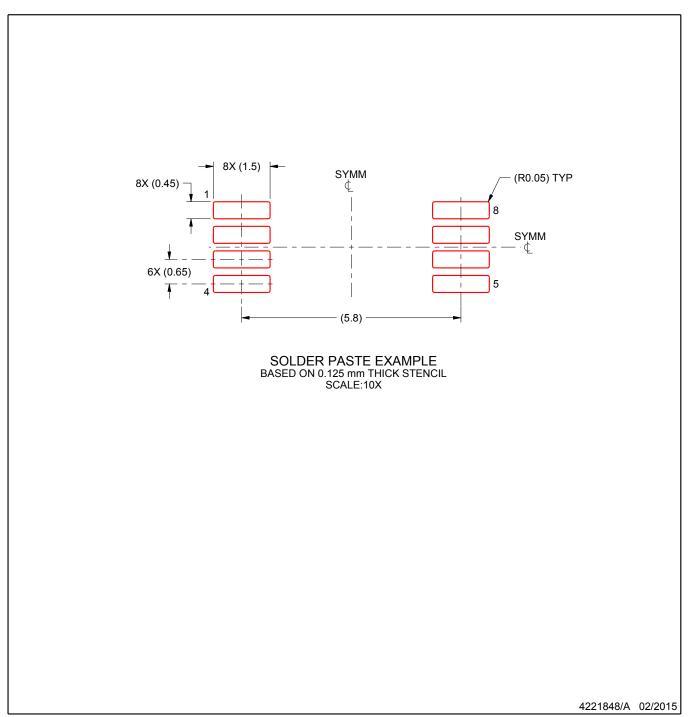
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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